TOSHIBA

2017-10-30 Rev.1.0

RD Number: RD112

RD Title: TB67S149FG Evaluation circuit

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	VM	1		ST-1-3	MAC8	Check pin		
2	VDD	1		ST-1-3	MAC8	Check pin		
3	GND	6		ST-1-3	MAC8	Check pin		
4	DMODE0	1		ST-1-3	MAC8	Check pin		
5	DMODE1	1		ST-1-3	MAC8	Check pin		
6	DMODE2	1		ST-1-3	MAC8	Check pin		
7	RESET	1		ST-1-3	MAC8	Check pin		
8	CLK	1		ST-1-3	MAC8	Check pin		
9	ENABLE	1		ST-1-3	MAC8	Check pin		
10	CW/CCW	1		ST-1-3	MAC8	Check pin		
11	COMA	1		ST-1-3	MAC8	Check pin		
12	OUTA+	1		ST-1-3	MAC8	Check pin		
13	OUTA-	1		ST-1-3	MAC8	Check pin		
14	OUTB-	1		ST-1-3	MAC8	Check pin		
15	OUTB+	1		ST-1-3	MAC8	Check pin		
16	COMB	1		ST-1-3	MAC8	Check pin		
17	VCOM	1		ST-1-3	MAC8	Check pin		
18	VCC	1		ST-1-3	MAC8	Check pin		
19	VREF	1		ST-1-3	MAC8	Check pin		
20	OSCM	1		ST-1-3	MAC8	Check pin		
21	ERR	1		ST-1-3	MAC8	Check pin		
22	MO	1		ST-1-3	MAC8	Check pin		
23	ZD	1		CMZ36	toshiba	Zener diode		
24	RVREF1	0						✓
25		0						✓
26		2		PD-10	MAC8	Socket pin		

27	RVREF2	0						✓
28		0						✓
29		2		PD-10	MAC8	Socket pin		
30	RERR	1	10kΩ,3.2mm×1.6mm	RK73B2BTTD103J	koa			
31		0	10kΩ,2.54mm pitch			Leaded resistor		✓
32	RMO	1	10kΩ,3.2mm×1.6mm	RK73B2BTTD103J	koa			
33		0	10kΩ,2.54mm pitch			Leaded resistor		✓
34	ROSCM	0	3.2mm×1.6mm					✓
35		1	10kΩ,2.54mm pitch	MFS1/4CC1002F	koa	Leaded resistor		
36		2		PD-10	MAC8	Socket pin		
37	CVM1	1	100uF/50V/YK,φD×L(mm)=8×11.5	KMG50VB100M	NIPPON CHEMI-CON	Electrolytic capacitor		
38	CVM2	1	0.1uF,3.2mm×1.6mm	GRM319R72A104KA01D	murata	Chip capacitor		
39		0	0.1uF	RDEF11H104Z0K1H01B	murata	Ceramic capacitor		✓
40	CVDD	1	>10V 10μF	KMG50VB10M	NIPPON CHEMI-CON	Electrolytic capacitor		
41	CVCC	1		GRM319R72A104KA01D	murata	Chip capacitor		
42	C1	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
43	C2	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
44	C3	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
45	C4	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
46	C5	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
47	C6	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
48	C7	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
49	C9	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
50	C13	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
51	C15	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
52	C17	0	0.1uF			Chip capacitor	3.2mm×1.6mm	✓
53	JP1	1	XJ8B-0911 etc	2130S1*2GSE	linkman	Jumper		
54		1	M7567-05 etc	2180BBA	linkman	Jumper Short		
55	SW1	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
56	(DMODE0)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		
57	SW2	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
58	(DMODE1)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		
59	SW3	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
60	(DMODE2)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		

61	SW4	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
62	(RESET)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		
63	SW5	0	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		✓
64	(CLK)	0	M7567-05 etc	2180BBA	linkman	Jumper Short		✓
65	SW6	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
66	(ENABLE)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		
67	SW7	1	XJ8B-0911 etc	2130S1*3GSE	linkman	Jumper		
68	(CW/CCW)	1	M7567-05 etc	2180BBA	linkman	Jumper Short		
69	CVREF	1	0.1uF	GRM319R72A104KA01D	murata	Chip capacitor	3.2mm×1.6mm	
70	CON1	3		1760510000	Weidmuller	ｺﾈｸﾀ		
71	IC1	1		TB67S149FG	toshiba	IC		
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